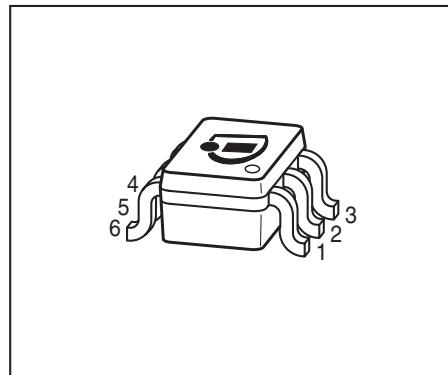


NPN Silicon RF Transistor

- For broadband amplifiers up to 1 GHz at collector currents from 1 mA to 20 mA
- BFS17S: For orientation in reel see package information below
- Pb-free (RoHS compliant) package



ESD (Electrostatic discharge) sensitive device, observe handling precaution!

Type	Marking	Pin Configuration						Package
BFS17S	MCs	1=B1	2=E1	3=C2	4=B2	5=E2	6=C1	SOT363

Maximum Ratings at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CEO}	15	V
Collector-base voltage	V_{CBO}	25	
Emitter-base voltage	V_{EBO}	2.5	
Collector current	I_C	25	mA
Peak collector current, $f = 10 \text{ MHz}$	I_{CM}	50	
Total power dissipation ¹⁾	P_{tot}	280	mW
$T_S \leq 93^\circ\text{C}$			
Junction temperature	T_J	150	$^\circ\text{C}$
Ambient temperature	T_A	-65 ... 150	
Storage temperature	T_{Stg}	-65 ... 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ²⁾	R_{thJS}	≤ 240	K/W

¹ T_S is measured on the collector lead at the soldering point to the pcb

²For calculation of R_{thJA} please refer to Application Note AN077 (Thermal Resistance Calculation)

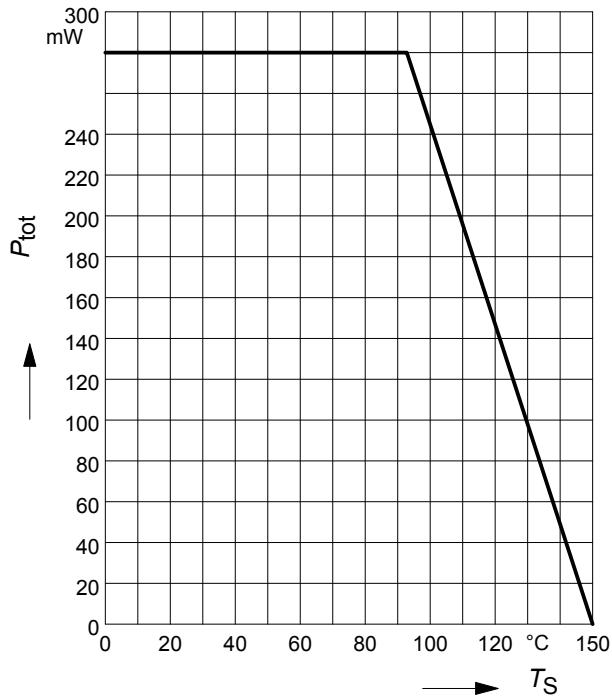
Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Collector-emitter breakdown voltage $I_C = 1 \text{ mA}, I_B = 0$	$V_{(\text{BR})\text{CEO}}$	15	-	-	V
Collector-base cutoff current $V_{CB} = 10 \text{ V}, I_E = 0$ $V_{CB} = 25 \text{ V}, I_E = 0$	I_{CBO}	-	-	0.05 10	μA
Emitter-base cutoff current $V_{EB} = 2.5 \text{ V}, I_C = 0$	I_{EBO}	-	-	100	
DC current gain $I_C = 2 \text{ mA}, V_{CE} = 1 \text{ V}$, pulse measured $I_C = 25 \text{ mA}, V_{CE} = 1 \text{ V}$, pulse measured	h_{FE}	40 20	- 70	150 -	-
Collector-emitter saturation voltage $I_C = 10 \text{ mA}, I_B = 1 \text{ mA}$	V_{CEsat}	-	0.1	0.4	V

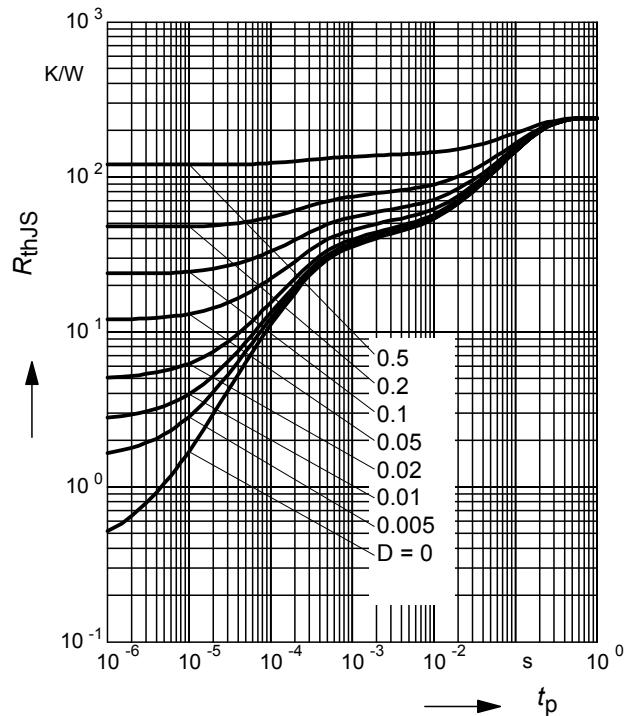
Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics (verified by random sampling)					
Transition frequency	f_T	1	1.4	-	GHz
$I_C = 2 \text{ mA}, V_{CE} = 5 \text{ V}, f = 200 \text{ MHz}$		1.3	2.5	-	
$I_C = 25 \text{ mA}, V_{CE} = 5 \text{ V}, f = 200 \text{ MHz}$					
Collector-base capacitance $V_{CB} = 5 \text{ V}, f = 1 \text{ MHz}, V_{BE} = 0$, emitter grounded	C_{cb}	-	0.55	0.8	pF
Collector emitter capacitance $V_{CE} = 5 \text{ V}, f = 1 \text{ MHz}, V_{BE} = 0$, base grounded	C_{ce}	-	0.2	-	
Emitter-base capacitance $V_{EB} = 0.5 \text{ V}, f = 1 \text{ MHz}, V_{CB} = 0$, collector grounded	C_{eb}	-	0.9	1.45	
Minimum noise figure $I_C = 2 \text{ mA}, V_{CE} = 5 \text{ V}, Z_S = 50 \Omega$, $f = 800 \text{ MHz}$	NF_{\min}	-	3	5	dB
Transducer gain $I_C = 20 \text{ mA}, V_{CE} = 5 \text{ V}, Z_S = Z_L = 50\Omega$, $f = 500 \text{ MHz}$	$ S_{21e} ^2$	-	14	-	dB
Third order intercept point at output $V_{CE} = 5 \text{ V}, I_C = 20 \text{ mA}, f = 800 \text{ MHz}$, $Z_S = Z_{\text{Sopt}}, Z_L = Z_{\text{Lopt}}$	IP_3	-	22.5	-	dBm
1dB compression point $I_C = 20 \text{ mA}, V_{CE} = 5 \text{ V}, Z_S = Z_L = 50\Omega$, $f = 800 \text{ MHz}$	$P_{-1\text{dB}}$	-	11	-	-

Total power dissipation $P_{\text{tot}} = f(T_S)$

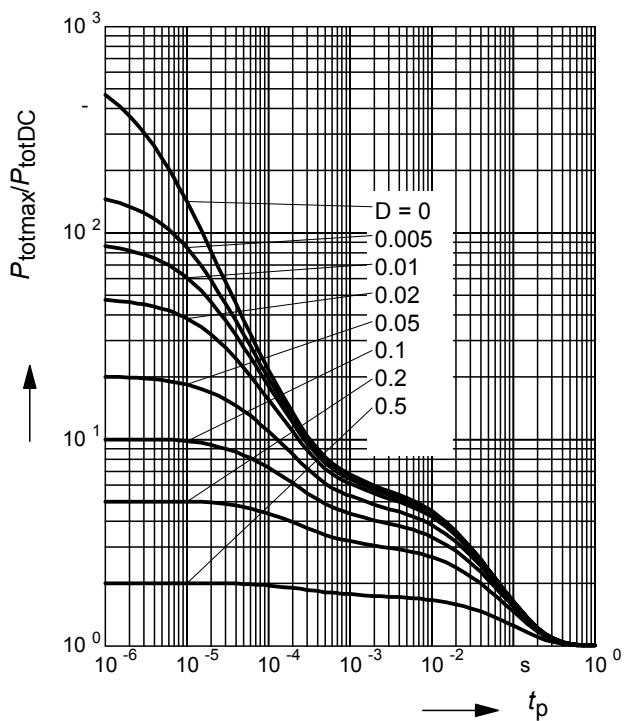


Permissible Pulse Load $R_{\text{thJS}} = f(t_p)$



Permissible Pulse Load

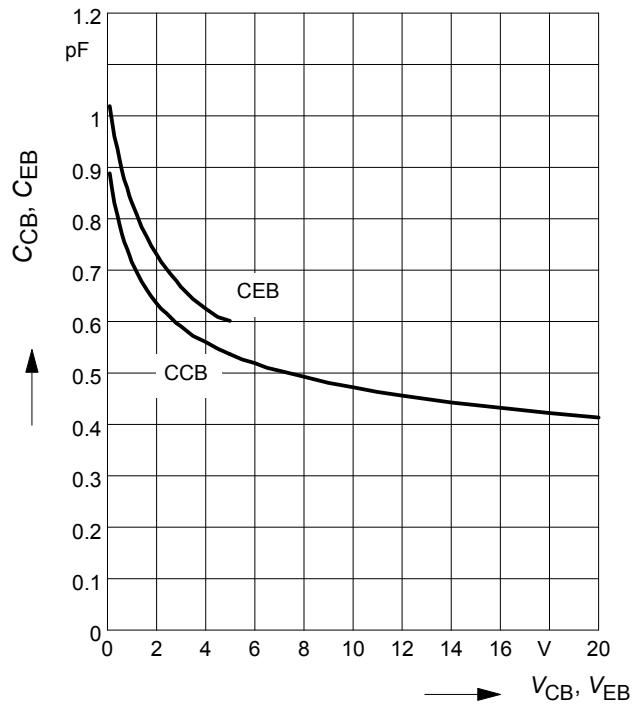
$P_{\text{totmax}}/P_{\text{totDC}} = f(t_p)$



Collector-base capacitance $C_{\text{cb}} = f(V_{\text{CB}})$

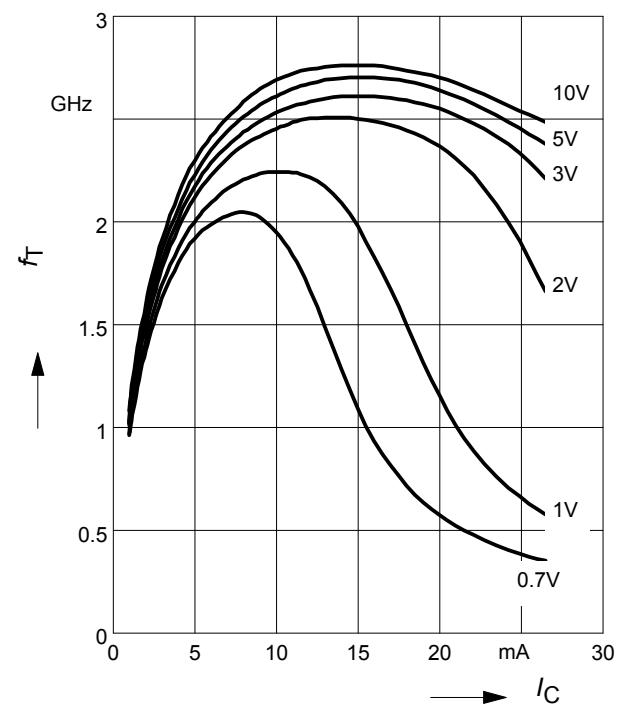
Emitter-base capacitance $C_{\text{eb}} = f(V_{\text{EB}})$

$f = 1 \text{ MHz}$

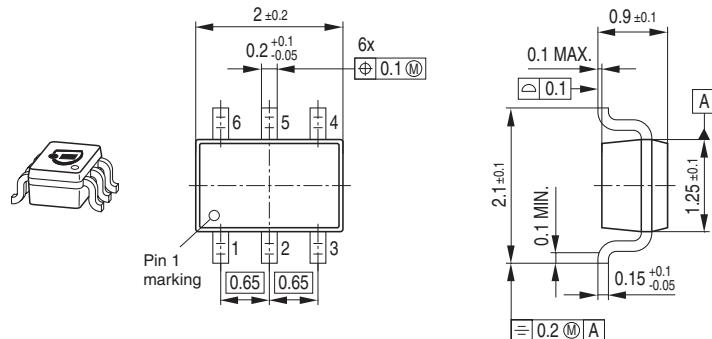


Transition frequency $f_T = f(I_C)$

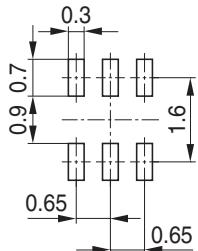
V_{CE} = parameter



Package Outline

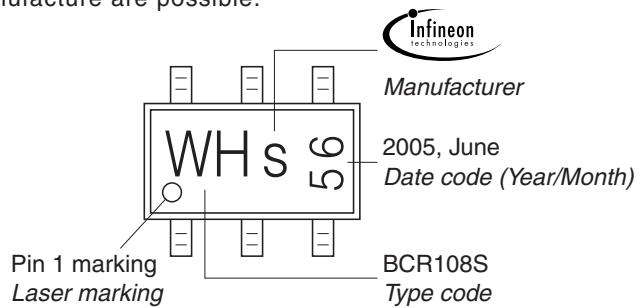


Foot Print



Marking Layout (Example)

Small variations in positioning of Date code, Type code and Manufacture are possible.

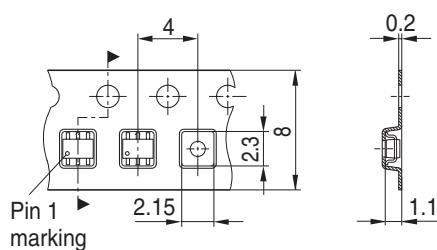


Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel

Reel ø330 mm = 10.000 Pieces/Reel

For symmetric types no defined Pin 1 orientation in reel.



Edition 2009-11-16

Published by
Infineon Technologies AG
81726 Munich, Germany

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